12/06/2015 503598410

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3645040

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yu-Ru Yang	11/20/2015
Huai-Tzu Chiang	11/20/2015
Sheng-Hao Lin	11/20/2015
Shih-Hsien Huang	11/27/2015
Chien-Hung Chen	11/20/2015
Chun-Yuan Wu	11/20/2015
Cheng-Tzung Tsai	11/20/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14960430

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Patent.admin.uspto.cr@naipo.com Email:

WINSTON HSU **Correspondent Name:** Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2604USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	12/06/2015

Total Attachments: 14

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Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here this declaration is directed to:	by declare that:				
☑ The attached application, or					
☐ United States application nu	mber	fi	led on	7	or
☐ PCT international application	number		_filed on		
The above-identified application was	made or authorized	to be made by	me.		
I believe that I am the original inventor application.	or or an original joint	inventor of a cl	aimed invention i	in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement mad sonment of not more	de in this declar e than five (5) ye	ration is punishab ears, or both.	ole	
In consideration of the payment by	UNITED MICROE	ELECTRONIC	CS having a p	ostal addre	ess of
No.3, Li-Hsin Road 2, Science	-Based Industria	I Park, Hsin-	Chu City 300,	Taiwan,	R.O.C.
(referred to as "ASSIGNEE" below) to acknowledged, and for other good and I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, and I hereby covenant that no assignment entered into which would conflict with I further covenant that ASSIGNEE with	d valuable considerand the second to any and all implication and, in and to, a any continuations, od as to Letters Pater t, sale, agreement of this assignment;	ation. Successors and rovements which the successors and rovements which the successor is a successor of the	assignees of the ch are disclosed in to be obtained for art, divisions, reported as been or will appropriately with all per	ASSIGNE n the for said newals, thereof. be made o	E
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representatives any and all papers, ir maintain, issue and enforce said appl equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	lication, said invention cessary or desirable	on and said Lett to carry out the	ers Patent and s	aid of. (Date of	sig n ing)
Note: An application data sheet (PTO inventive entity, must accompany this	/SB/14 or equivalent form. Use this form	t), including nar for <u>each additio</u>	ming the entire onal inventor.		

Page 1 of 14

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Yu-Ru Yang	Date:	NOV 2 0 2015		
Signature:	y-Ry	Made (1981) (1981) (1981) (1981) (1981) (1981) (1981) (1981) (1981) (1981) (1981) (1981) (1981) (1981) (1981)		- 4-141 - - 1 -14-1-1	

Page 2 of 14

Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	n number	filed on	***************************************
The above-identified application was	s made or authorized to be made l	by me.	44-4-4
I believe that I am the original invent application.	or or an original joint inventor of a	claimed invention in the	Э
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this dec isonment of not more than five (5)	laration is punishable years, or both.	
In consideration of the payment by	UNITED MICROELECTRON CORP.	IICS having a postal	l address of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu City 300, Taiv	wan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ 1.0 and valuable consideration.	0), the receipt of which i	is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica- invention by the above application or substitutes, or extensions thereof, an	nd to any and all improvements wi tion and, in and to, all Letters Pate r any continuations, continuation-in	nich are disclosed in the ent to be obtained for sa n-part divisions renewa	e uid
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or encumbrand n this assignment;	ce has been or will be m	nade or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Patent and le stify as to the same in any interfer	egal equivalents as may rence, litigation proceedi	/ he
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said Locessary or desirable to carry out t	etters Patent and said he proposes thereof.	ate of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including n s form. Use this form for <u>each add</u>	aming the entire	

Page 3 of 14

LEGAL NAM	ME OF INVENTOR(ASSIGN	OR)					
Inventor:	Huai-Tzu Chiang		Date:	VOV	20	2015	
Signature:	<u> </u>	572u	Chian	<u></u>			
		1		A.			

Page 4 of 14

NPO#NAU-P2604-USA:0 CUST#UMCD-2015-0479

Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed	on	, or
☐ PCT international application	number		ed on	
The above-identified application was	made or authorized to	be made by me.		
I believe that I am the original inventorapplication.	or or an original joint in	ventor of a claim	ed invention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made sonment of not more th	in this declaratio nan five (5) years	n is punishable , or both.	
In consideration of the payment by	UNITED MICROEL CORP.	ECTRONICS	having a postal	address of
No.3, Li-Hsin Road 2, Science	-Based Industrial F	Park, Hsin-Chu	 u City 300, Taiw	van, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	l of the sum of One D d valuable consideratio	ollar (\$ 1.00), the on.	receipt of which is	hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	id to any and all improv ion and, in and to, all L any continuations, cor	rements which ar etters Patent to b itinuation-in-part.	e disclosed in the be obtained for said divisions, renewal	d Is
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement or e this assignment;	ncumbrance has	been or will be ma	ade or
I further covenant that ASSIGNEE wi and documents relating to said inven- known and accessible to I and will te- related thereto and will promptly exec-	tion and said Letters Pa stify as to the same in a	atent and legal ed any interference,	quivalents as may litigation proceedir	be
representatives any and all papers, ir maintain, issue and enforce said appl equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	lication, said invention cessary or desirable to	and said Letters carry out the pro	Patent and said poses thereof.	te of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	n/SB/14 or equivalent), form. Use this form fo	including naming r <u>each additional</u>	the entire inventor.	

Page 5 of 14

Inventor: Sheng-Hao Lin Date: NOV 2 0 2015

Signature: Sheng-Hao Lin Date: NOV 2 0 2015

Page 6 of 14

Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☐ United States application nu	mber	filed on	, or
□ PCT international application		filed on	,
The above-identified application was	made or authorized to be made b	by me.	
I believe that I am the original inventorapplication.	or or an original joint inventor of a	claimed invention in the	
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	l of the sum of One Dollar (\$ 1.00 d valuable consideration.	0), the receipt of which is he	reby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	nd to any and all improvements what tion and, in and to, all Letters Pate any continuations, continuation-ir	nich are disclosed in the ent to be obtained for said n-part, divisions, renewals.	EE
I hereby covenant that no assignment entered into which would conflict with	rt, sale, agreement or encumbrand this assignment;	ce has been or will be made	or
I further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and said Letters Patent and le stify as to the same in any interfer	egal equivalents as may be ence, litigation proceeding	ts
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and said Locessary or desirable to carry out t	etters Patent and said he proposes thereof.	f signing)
Note: An application data sheet (PTC inventive entity, must accompany this			

Page 7 of 14

NPO#NAU-P2604-USA:0 CUST#UMCD-2015-0479

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Shih-Hsien Huang	Date:	NOV 2 7 2015	
Signature:	Shih-Msien Muang			

Page 8 of 14

Title of Invention: **SEMICONDUCTOR STRUCTURE**

As the below named inventor, I here This declaration is directed to:	by declare that:				
☑ The attached application, or					
☐ United States application nu	filed	filed on , or			
☐ PCT international application number			ed on		
The above-identified application was	made or authorized to	be made by me.	•.		
I believe that I am the original invent application.	or or an original joint ir	nventor of a claim	ed invention in the		
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made isonment of not more t	e in this declaration han five (5) years	n is punishable , or both.		
In consideration of the payment by	UNITED MICROEI CORP.	ECTRONICS	having a postal a	address of	
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-Ch	u City 300, Taiw	an, R.O.C.	
(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.					
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.					
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or on this assignment;	encumbrance has	s been or will be ma	ide or	
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ition and said Letters F stify as to the same in	Patent and legal e any interference,	quivalents as may l	be	
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	lication, said invention cessary or desirable to	and said Letters carry out the pro	Patent and said poses thereof.	te of signing)	
Note: An application data sheet (PTC inventive entity, must accompany thi	D/SB/14 or equivalent) s form. Use this form fo	, including naming or each additional	the entire inventor.		

Page 9 of 14

NPO#NAU-P2604-USA:0 CUST#UMCD-2015-0479

Inventor: Chien-Hung Chen

Date: NOV 2 0 2015

Signature: Chien-Hung Chen

Date: NOV 2 0 2015

Page 10 of 14

NPO#NAU-P2604-USA:0 CUST#UMCD-2015-0479

Title of Invention: **SEMICONDUCTOR STRUCTURE**

As the below named inventor, I here This declaration is directed to:	by declare that:				
☑ The attached application, or					
☐ United States application nu	file	filed on			
☐ PCT international application		filed on			
The above-identified application was	made or authorize	ed to be made by m	ne.		
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I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	I false statement m sonment of not mo	ade in this declara are than five (5) yea	tion is punishable ars, or both.		
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	l of the sum of Or d valuable conside	ne Dollar (\$ 1.00), t eration.	he receipt of whic	h is hereby	
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I hereby covenant that no assignmen entered into which would conflict with	it, sale, agreement i this assignment;	or encumbrance h	as been or will be	made or	
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, ir maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said inven cessary or desirab	tion and said Lette le to carry out the p	rs Patent and said proposes thereof.	i (Date of signing)	
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.					

Page 11 of 14

F#NPO-P0002E-US1201

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Chun-Yuan Wu	Date:	NOV 2 0 2015		
Signature:	Chem Yuan Wy				

Page 12 of 14

NPO#NAU-P2604-USA:0 CUST#UMCD-2015-0479 F#NPO-P0002E-US1201 DSC0-104U010860

Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:				
☑ The attached application, or					
☐ United States application number		filed on		, or	
☐ PCT international application number		filed on			
The above-identified application was	made or authorized to	be made by me.			
I believe that I am the original invent application.	or or an original joint in	ventor of a claime	d invention in the		
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made isonment of not more th	in this declaration an five (5) years,	is punishable or both.		
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I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention accessary or desirable to	and said Letters F carry out the prop	atent and said oses thereof.	e of signing)	
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>					

Page 13 of 14

NPO#NAU-P2604-USA:0 CUST#UMCD-2015-0479

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	Cheng-Tzung Tsai	Date:	NOV 2 0 2015		
Signature:	Chorg Trung Tsai				

Page 14 of 14

F#NPO-P0002E-US1201 DSC0-104U010860

NPO#NAU-P2604-USA:0 CUST#UMCD-2015-0479

RECORDED: 12/06/2015